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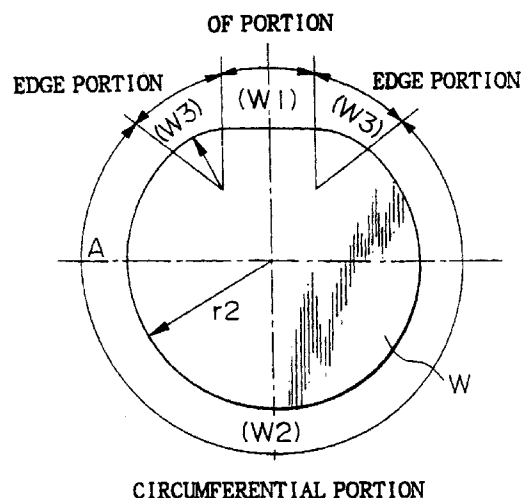
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(54) Wafer processing

(57) A method for processing a peripheral chamfered portion of a wafer (W) having an orientation flat portion (W1), comprises: a first honing step for honing the orientation flat portion (W1) of the wafer (W) by relatively pressing the orientation flat portion (W1) against a cylindrical honing stone (21) with a first pressing force (F1), while rotating the wafer (W) at a first rotational speed (Ns1) and rotating the honing stone (21); a second honing step for honing the circumferential portion (W2) of the wafer (W) by relatively pressing the circumferential portion (W2) against the cylindrical honing stone (21) with a second pressing force (F2), while rotating the wafer (W) at a second rotational speed (Ns2) and rotating the honing stone (21); a third honing step for honing the edge portions (W3) of the wafer (W) by relatively pressing the edge portions (W3) against the cylindrical honing stone (21) with a third pressing force (F3), while rotating the wafer (W) at a third rotational speed (Ns3) and rotating the honing stone (21); and a polishing step for polishing the honed orientation flat portion (W1), the honed circumference portion (W2) and the honed edge portions (W3); wherein the first, second and third rotational speeds (Ns1, Ns2 and Ns3), of the wafer (W) are different from one another; or the first, second and third pressing forces (F1, F2 and F3) are different from one another.

FIG.1**EP 0 832 717 A3**



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EUROPEAN SEARCH REPORT

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Category	Citation of document with indication, where appropriate, of relevant passages	Relevant to claim	CLASSIFICATION OF THE APPLICATION (Int.Cl.6)
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			TECHNICAL FIELDS SEARCHED (Int.Cl.6)
			B24B
The present search report has been drawn up for all claims			
Place of search		Date of completion of the search	Examiner
THE HAGUE		22 September 1998	Garella, M
CATEGORY OF CITED DOCUMENTS X : particularly relevant if taken alone Y : particularly relevant if combined with another document of the same category A : technological background O : non-written disclosure P : intermediate document T : theory or principle underlying the invention E : earlier patent document, but published on, or after the filing date D : document cited in the application L : document cited for other reasons & : member of the same patent family, corresponding document			

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